

L Number	Hits	Search Text	DB	Time stamp
1	34	Benzocyclobutene with (photoresist photoimageable prepreg)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:22
2	326641	Benzocyclobutene with solder mask	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:22
3	0	Benzocyclobutene with solder with mask	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:22
4	327599	polyimide with solder mask	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:22
5	133	polyimide with solder with mask	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:35
6	1250	(257/690).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:35
7	28	(Benzocyclobutene with (photoresist photoimageable prepreg)) and photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:59
8	18	("5477933" "5627405" "5767010" "5786270" "5817541" "5844304" "5858815" "5862816" "5863812" "5872051" "5877079" "5879964" "5886398" "5889332" "5891795" "5892273" "5892290" "5987744").PN.	USPAT	2002/11/09 15:35
9	816	(257/691).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:59
10	976	(257/698).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:59
11	1195	(257/700).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:59
14	34	((257/700).CCLS.) and (metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepreg)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 16:01
12	10	(metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepreg) and ((257/691).CCLS.)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 16:01
13	38	((257/698).CCLS.) and (metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepreg)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 16:31
15	3	("6441487" "6361926").pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 16:32
16	2	("6441487" "6361926").pn.	USPAT	2002/11/09 16:32

-	2056	257/690	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:15
-	1250	257/690.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:16
-	230	257/690.ccls. and substrate with pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:18
-	0	insulating with substra with pad and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:19
-	1142	insulating with substrate with pad and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:19
-	116	(insulating with substrate with pad and 257/\$.ccls.) and foil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:21
-	26119	foil with adhesi\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:21
-	25980	foil with adhesi\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:21
-	1263	(foil with adhesi\$5) and insulating with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:22
-	158	((foil with adhesi\$5) and insulating with substrate) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:26
-	9	foil with dentritic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:33
-	117	(metal foil wiring pad pattern) with rough\$5 same adhes\$7 and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:35
-	90	(metal foil wiring pad pattern) with rough\$5 same adhes\$7 and 257/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 11:34
-	7	("4816426" "5329423" "5523586" "5661088" "5726500" "5801447" "5872393").PN.	USPAT	2002/11/09 11:00

-	17	("3380155" "3823348" "4021838" "4122479" "4250520" "4675717" "4774630" "5086327" "5187715" "5212406" "5228777" "5289637" "5311278" "5326984" "5463249" "5506418" "5543641").PN.	USPAT	2002/11/09 11:08
-	11	5086327.URPN.	USPAT	2002/11/09 11:08
-	12	5726500.URPN.	USPAT	2002/11/09 11:08
-	1881	(metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepeg) and 257/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 16:00
-	0	((metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepeg) and 257/\$.ccls.) and springboard	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 11:39
-	564	((metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepeg) and 257/\$.ccls.) and copper	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 11:39
-	501	((metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepeg) and 257/\$.ccls.) and copper) and (aluminum gold silver nickel chrome)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:01
-	19	("4462534" "5024372" "5220200" "5261593" "5293067" "5346861" "5381848" "5388327" "5455390" "5504277" "5539153" "5541460" "5547740" "5564617" "5604379" "5608262" "5701032" "5736456" "5814894").PN.	USPAT	2002/11/09 11:42